

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s):	Virgil Cotoco Ararao et al.	Confirmation No.: 6546
Application No.:	10/721,916	Group Art Unit: 2893
Filed:	11/24/2003	Examiner: Thanh T. Nguyen
Title:	FABRICATION METHOD FOR SEMICONDUCTOR PACKAGE HEAT SPREADERS	

**TRANSMITTAL AND REQUEST FOR CORRECTED/SUPPLEMENTAL NOTICE
OF ALLOWANCE**

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir/Madam:

Applicant hereby respectfully submits notice of an error in the Title of Invention on the Notice of Allowance received for the above-referenced patent application.

The Notice of Allowance mailed on April 7, 2009, shows the Title as "Method of Fabricating a Semiconductor Package Heat Spreaders". However, in an Amendment filed December 13, 2005 and received by the USPTO on December 13, 2005, Applicant amended the Title to "Fabrication Method for Semiconductor Package Heat Spreaders".

Applicant respectfully requests a Corrected or Supplemental Notice of Allowance with the correct Title.

At any time during the pendency of this application, please charge any fees required or credit any overpayment to Deposit Account 50-0374 pursuant to 37 CFR 1.25.

Respectfully submitted,



Mikio Ishimaru
Reg. No. 27,449
June 14, 2009

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CERTIFICATE OF FAXING/TRANSMISSION (37 C.F.R.1.8a)

I hereby certify that this correspondence is on the date shown below being:

☒ Submitted to the: Office of Initial Patent Examination's Filing Receipt Corrections, Commissioner for Patents P.O. Box 1450, Alexandria, VA 22313-1450 via Electronic Filing System

Date: June 14, 2009

Signature


Vickie Ishimaru